

Amendments to the Claims:

Claim 1 (original): A semiconductor device comprising:

 a semiconductor chip having over a main surface thereof an integrated circuit and plural electrodes;

 plural leads having end portions on one side fixed to a back surface of said semiconductor chip and opposite end portions used as external terminals;

 plural wires for connecting the plural electrodes on said semiconductor chip with the plural leads positioned outside said semiconductor chip;

 and

 a resin sealing member for sealing said semiconductor chip, portions of said plural leads and said plural wires, the opposite end portions of said plural leads being exposed from a back surface of the resin sealing member.

Claim 2 (original): The semiconductor device according to claim 1, wherein said external terminals comprise first external terminals arranged along side faces of the resin sealing member and second external terminals arranged inside said first external terminals and each disposed between adjacent ones of said first external terminals.

Claim 3 (original): The semiconductor device according to claim 1, wherein the plural leads comprise plural first leads end portions on one side of which are positioned outside said semiconductor chip and plural second leads each disposed between adjacent ones of said first leads and end portions on one

side of which are fixed to the back surface of the semiconductor chip,
wherein said plural first leads include said first external terminals respectively,
and
wherein said plural second leads include said second external terminals
respectively.

Claim 4 (original): The semiconductor device according to claim 1, further comprising a spacer fixed to an upper surface of said semiconductor chip and exposed partially from an upper surface of said resin sealing member.

Claim 5 (original): A semiconductor device comprising:
an insulating base;
a semiconductor chip having over a main surface thereof an integrated circuit and plural electrodes, the semiconductor chip being fixed over said insulating base;
plural leads end portions on one side of which are fixed to said insulating base and opposite end portions of which are used as external terminals;
plural wires for connecting the plural electrodes formed on said semiconductor chip with said plural leads positioned outside said insulating base;
and
a resin sealing member for sealing said insulating base, said semiconductor chip, portions of said plural leads and said plural wires, the opposite end portions of said leads being exposed from a back surface of the resin sealing member.

Claim 6 (original): The semiconductor device according to claim 5, wherein said external terminals comprise first external terminals arranged along side faces of the resin sealing member and second external terminals arranged inside said first external terminals and each disposed between adjacent ones of said first external terminals.

Claim 7 (original): The semiconductor device according to claim 6, wherein said plural leads comprise plural first leads end portions on one side of which are positioned outside said insulating base and plural second leads each disposed between adjacent ones of said first leads and end portions on one side of which are fixed to said insulating base,

wherein said plural first leads include the first external terminals respectively, and

wherein said plural second leads include said second external terminals respectively.

Claim 8 (original): The semiconductor device according to claim 5, further comprising a spacer fixed to an upper surface of said semiconductor chip and exposed partially from an upper surface of said resin sealing member.

Claims 9-19 (canceled)